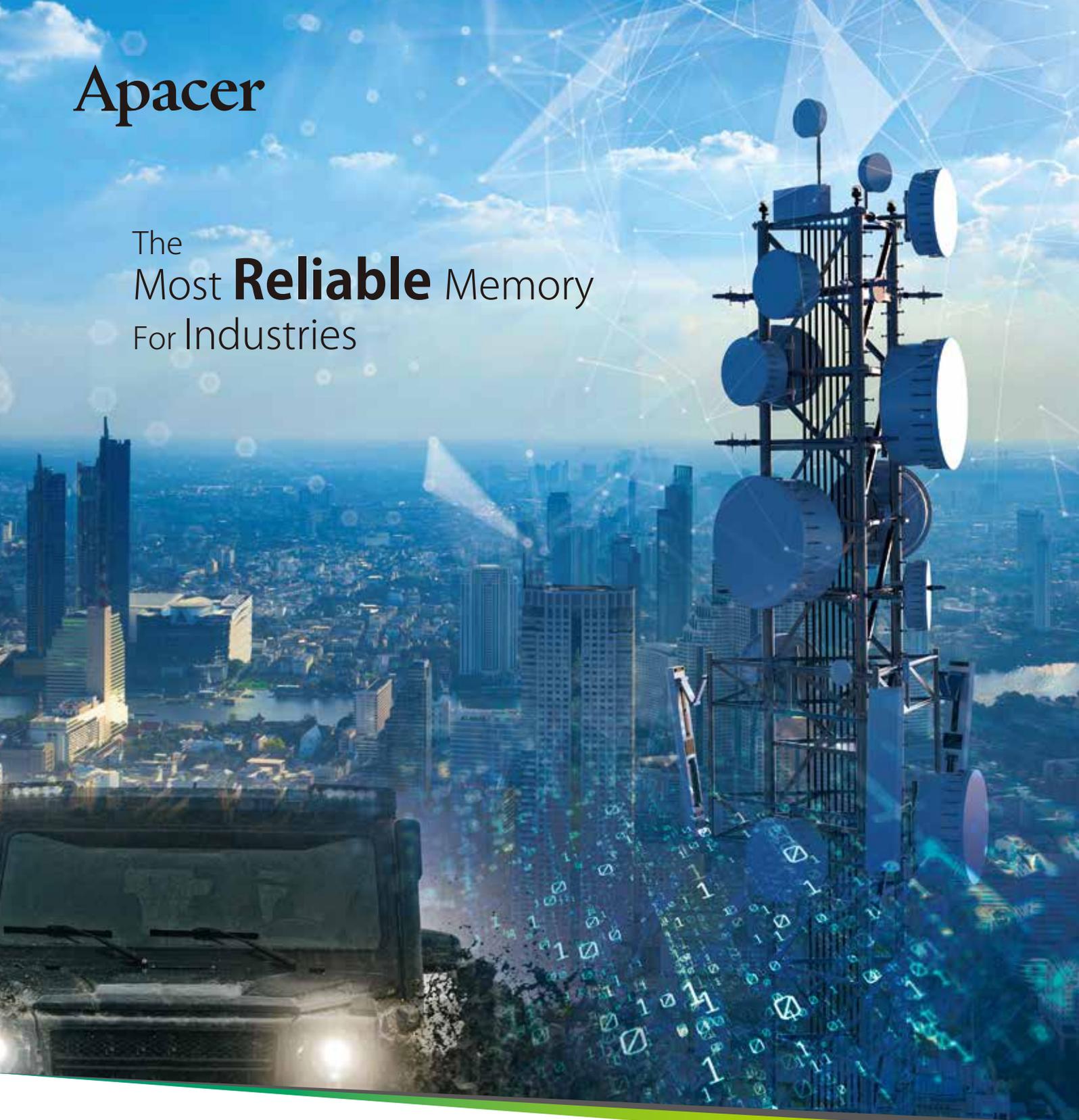


Apacer

The
Most **Reliable** Memory
For Industries



Industrial DRAM Solutions

industrial.apacer.com

Index

What Sets Apacer Apart?	02
Solutions for Extreme Environments	03
Technologies and Advantages	04
Apacer's DRAM Module Series	07
Embedded	07
Server/Workstation	08
Very Low Profile	10
Mini DIMM	12
Wide Temperature	13
Specialty	15
About Apacer	18



What Sets Apacer Apart?

Quality Assurance

- 100% reliable & compliant
 - Wide temperature test
 - Thermal shock test
 - Strict ORT (Ongoing Reliability Test)
 - Power cycle test
 - Humidity test
 - Altitude test
 - Reliability test (Vibration/Shock)

Extensive Experience

- Tier 1 industrial SSD & memory supplier; delivered over 340 million units
- Comprehensive experience in product customization (across industries)

Reliable Service

- Fixed BOM solution
- Longevity of supply, EOL & LTB notice
- Manufacturing in Taiwan protects IP

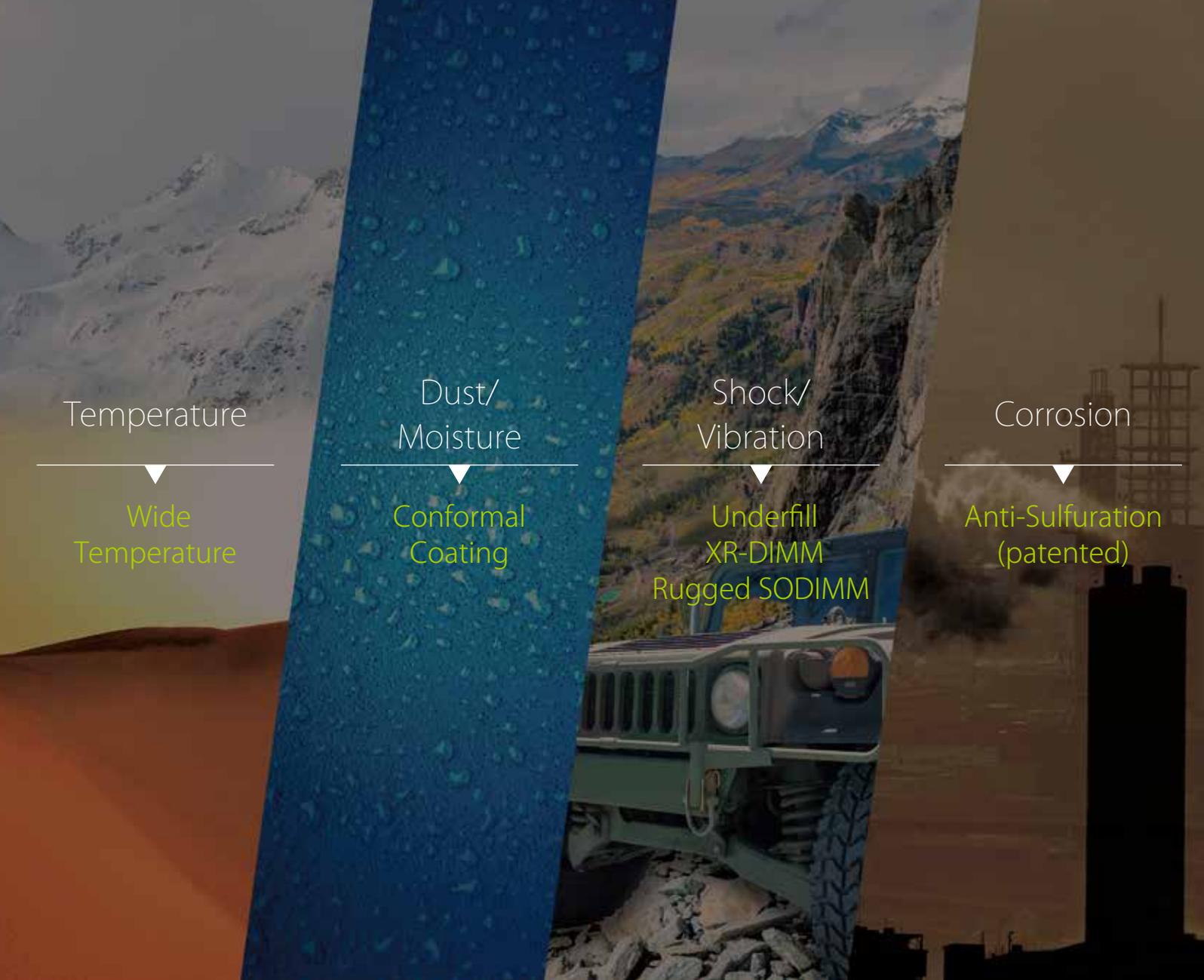
Professional Technique

- Strong HW/FW engineering know-how
- Customized design with a variety of solutions
- State-of-the-art technology



Trustworthy Supplier

- A global-scale service and maintenance system
- Responsive local FAE technical support
- 24/7 flexible and quick delivery service
- Complete RMA system



Temperature

Wide
Temperature

Dust/
Moisture

Conformal
Coating

Shock/
Vibration

Underfill
XR-DIMM
Rugged SODIMM

Corrosion

Anti-Sulfuration
(patented)

Solutions for Extreme Environments

Nowadays, as industrial memory products have been widely used in various kinds of applications, the need for memory modules that can maintain highly stable operating performance in harsh conditions is remarkably increasing.

As an industrial solution veteran and leading memory brand, Apacer always takes an outside-in perspective and strives for new breakthroughs, providing many value-added solutions and technologies for extreme environments to ensure product reliability, stability and durability.

Technologies and Advantages



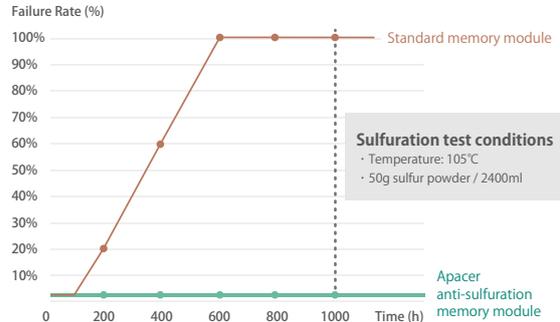
Anti-Sulfuration



Apacer's patented anti-sulfuration memory modules replace standard silver electrodes with an exclusive alloy which has passed the ASTM B809-95 anti-sulfuration test.

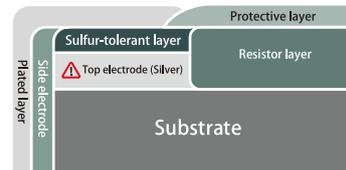
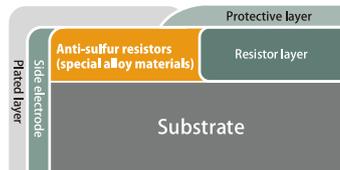
- World's first anti-sulfuration memory modules
- Solve corrosion problems effectively and increase overall system lifespan

Anti-sulfuration test



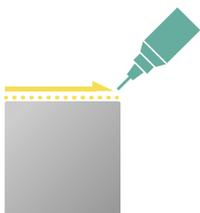
Anti-sulfuration technology comparison

	Apacer's advanced anti-sulfuration technology	Traditional anti-sulfuration technology
Method	Adopts exclusive and improved alloy materials replace normal electrode	Covers an sulfur-tolerant layer to protect the electrode
Advantages / Disadvantages	Reliable anti-sulfuration performance, improved product reliability and durability	Unstable anti-sulfuration performance due to process failure

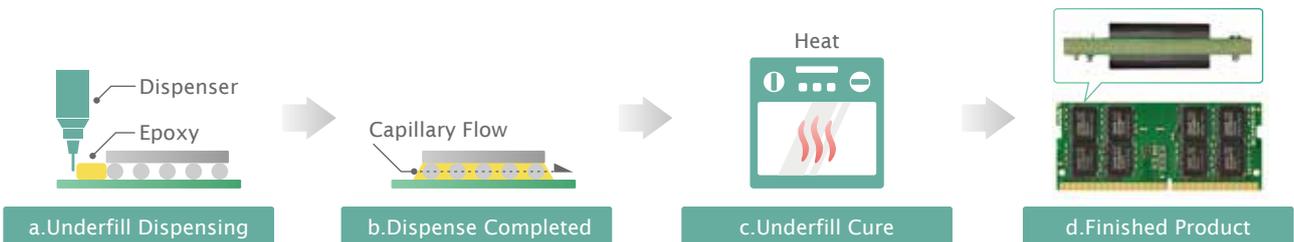


Underfill

Apacer provides underfill technology to increase product reliability and resistance to various thermal and mechanical shocks, ensuring that products continue to operate normally in high vibration and under extreme changes in environmental temperature.



- Strengthens the solder joints between solder balls and printed circuit board
- Increases the product's resistance against shock and vibration
- Reduces thermal stress damage
- Complies with MIL-STD-810G shock and vibration requirements
- Increases product reliability and lifespan



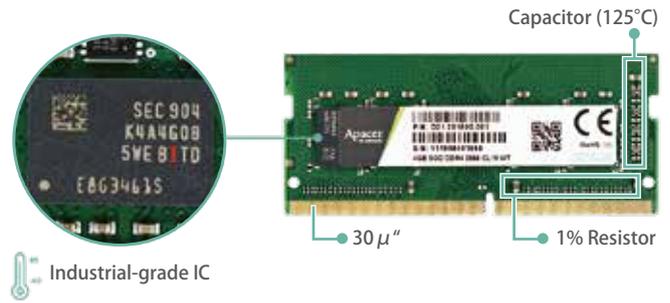


Wide Temperature

Especially designed for harsh climates and special environmental conditions.

- **Operating temperature range: $-40^{\circ}\text{C} \leq \text{TC} \leq 85^{\circ}\text{C}$**
- **All industrial-grade components (DRAM, PCB, resistors and capacitors) ensure stability and reliability**
- **High/Low temp. test / Temp. cycling test**
- **Power cycling test**

Insists on using industrial-grade DRAM ICs



Apacer's strengths of wide temperature memory

Apacer industrial-grade wide temp. memory		Standard memory (Commercial)
Industrial-grade ($-40 \sim +85^{\circ}\text{C}$) Suitable for extreme high and low temperature environment	◀ DRAM ▶	Commercial-grade ($0 \sim +85^{\circ}\text{C}$)
30 μm Avoids gold finger oxidation and ensures the stability of signal transmission	◀ PCB plating thickness ▶	3 μm
Up to $+125^{\circ}\text{C}$ Ensures more stable voltage supply in high-temperature environment	◀ Capacitor temp. specification ▶	$+85^{\circ}\text{C}$
$\pm 1\%$ tolerance Increases circuit stability and durability	◀ Resistor specification ▶	$\pm 5\%$ tolerance



30 μm
Gold Finger

30 μm Gold Finger

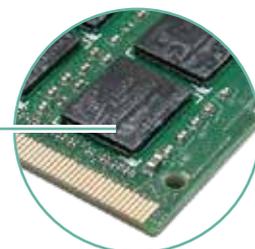
With the 30 μm gold plating, the connector interface is more reliable and can withstand the potential damages in industrial applications.



Conformal Coating

Enhances reliability of products by applying coatings on the surface of printed circuit boards. The protective film can safeguard devices from dust ingress and liquid immersion.

- **Uses automated spraying to maintain precise coating thickness**
- **Enhances product reliability**
- **Prolongs DRAM modules' lifespan**

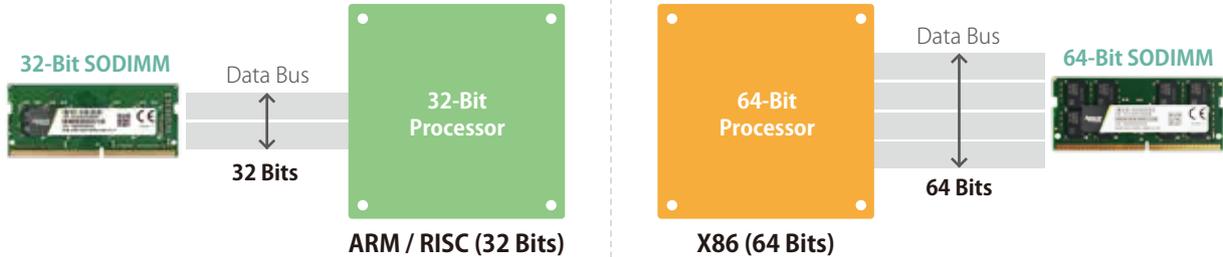


● Apacer DRAM module with conformal coating

32
Bit

32-Bit SODIMM

Mainly supports the ARM architecture. Unlike the 64-bit memory module that supports x86 system, the unique 32-bit SODIMM provides the 32-bit ARM architecture with another design option besides onboard memory.



Rugged

Extremely Rugged XR-DIMM

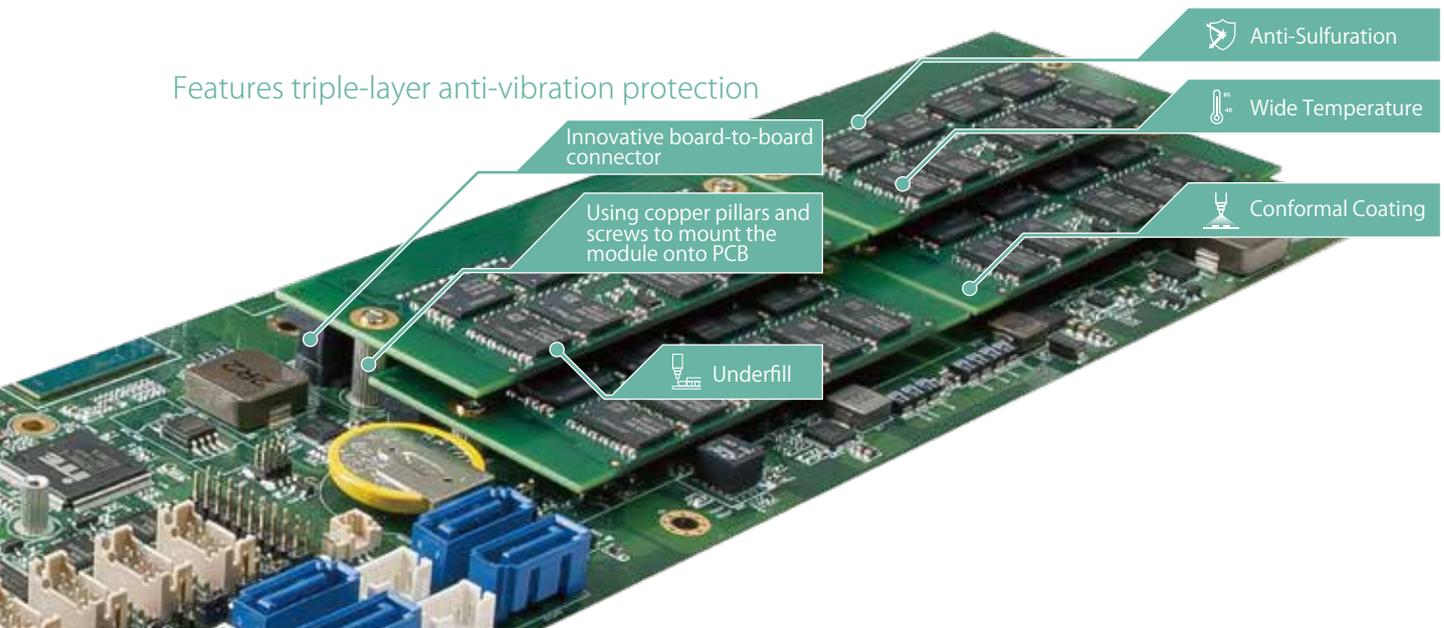
- Innovative board-to-board connector design
- Adopts highly durable 300-pin connector and mounting holes to improve the anti-vibration and anti-shock reliability
- Dual anti-shock and vibration certification: RTCA DO-160G / MIL-STD-810G
- Supports multiple protection technologies and value-added applications

Rugged Memory Comparison

	XR-DIMM Rugged Memory	Onboard memory
Anti-shock & anti-vibration ability	Great	Great
Memory upgradability	Yes	No
Repair difficulty	Easy	Difficult
RMA cost	Low	High
Stackable design	Yes	No
Motherboard space usage	Flexible	Uniform and inflexible

Supports multiple value-added applications

Features triple-layer anti-vibration protection



Embedded

UDIMM (Unbuffered DIMM)

- JEDEC-compliant design
- Applicable for desktop computers, industrial computers and embedded systems



Model	DDR4 UDIMM	DDR3 UDIMM	DDR2 UDIMM	DDR UDIMM
Module Type	UDIMM	UDIMM	UDIMM	UDIMM
Memory Technology	DDR4	DDR3	DDR2	DDR
Frequency	2133/2400/2666/2933/3200	1066/1333/1600/1866	533/667/800	266/333/400
Density	2G/4G/8G/16G/32G	1G/2G/4G/8G/16G	1G/2G/4G	512M/1G
Voltage	1.2v	1.5v/1.35v	1.8v	2.5v/2.6v
Pin Count	288-Pin	240-Pin	240-Pin	184-Pin
Width	64-Bit	64-Bit	64-Bit	64-Bit
PCB Height	1.23"	1.18"	1.18"	1.25"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TA=0°C to 70°C
Application	Gaming / Healthcare / IoT / Factory Automation			
Value-Added	 	 	 	

SODIMM (Small Outline DIMM)

- JEDEC-compliant design
- Applicable for space-constraint systems, such as notebook computers, small-size industrial computers and embedded systems



Model	DDR4 SODIMM	DDR3 SODIMM	DDR2 SODIMM	DDR SODIMM
Module Type	SODIMM	SODIMM	SODIMM	SODIMM
Memory Technology	DDR4	DDR3	DDR2	DDR
Frequency	2133/2400/2666/2933/3200	1066/1333/1600/1866	533/667/800	266/333/400
Density	2G/4G/8G/16G/32G	1G/2G/4G/8G/16G	1G/2G/4G	256M/512M/1G
Voltage	1.2v	1.5v/1.35v	1.8v	2.5v/2.6v
Pin Count	260-Pin	204-Pin	200-Pin	200-Pin
Width	64-Bit	64-Bit	64-Bit	64-Bit
PCB Height	1.18"	1.18"	1.18"	1.25"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TA=0°C to 70°C
Application	Gaming / IoT / Transportation / Factory Automation			
Value-Added	 	 	 	 

Server/Workstation

RDIMM (ECC Registered DIMM)

- Includes a register to enhance clock, command and control signals
- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- Applicable for enterprise servers and cloud data centers



Model	DDR4 RDIMM	DDR3 RDIMM
Module Type	RDIMM	RDIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600/1866
Density	4G/8G/16G/32G/64G	1G/2G/4G/8G/16G
Voltage	1.2v	1.5v/1.35v
Pin Count	288-Pin	240-Pin
Width	72-Bit	72-Bit
PCB Height	1.23"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C
Application	Healthcare / Server & Networking	

Value-Added



LRDIMM (Load Reduced DIMM)

- Includes a register to enhance clock, command and control signals
- Enhanced data signal with placing data buffer
- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- Applicable for enterprise servers and cloud data centers



Model	DDR4 LRDIMM
Module Type	LRDIMM
Memory Technology	DDR4
Frequency	2666/2933/3200
Density	64G/128G
Voltage	1.2v
Pin Count	288-Pin
Width	72-Bit
PCB Height	1.23"
Operation Temperature	TC=0°C to 85°C
Application	Healthcare / Server & Networking

Value-Added



Server/Workstation

ECC UDIMM (ECC Unbuffered DIMM)

- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- Applicable for servers and workstations that require highly stable operation



Model	DDR4 ECC UDIMM	DDR3 ECC UDIMM	DDR2 ECC UDIMM
Module Type	ECC UDIMM	ECC UDIMM	ECC UDIMM
Memory Technology	DDR4	DDR3	DDR2
Frequency	2133/2400/2666/2933/3200	1066/1333/1600/1866	533/667/800
Density	4G/8G/16G/32G	1G/2G/4G/8G/16G	1G/2G/4G
Voltage	1.2v	1.5v/1.35v	1.8v
Pin Count	288-Pin	240-Pin	240-Pin
Width	72-Bit	72-Bit	72-Bit
PCB Height	1.23"	1.18"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C
Application	Healthcare / IoT / Server & Networking / Factory Automation		

Value-Added



ECC SODIMM (ECC Small Outline DIMM)

- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- Applicable for microservers, workstations, networking platforms and embedded systems



Model	DDR4 ECC SODIMM	DDR3 ECC SODIMM
Module Type	ECC SODIMM	ECC SODIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600/1866
Density	4G/8G/16G/32G	1G/2G/4G/8G/16G
Voltage	1.2v	1.5v/1.35v
Pin Count	260-Pin	204-Pin
Width	72-Bit	72-Bit
PCB Height	1.18"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C
Application	IoT / Server & Networking / Transportation / Factory Automation	

Value-Added



Very Low Profile

VLP UDIMM (Very Low Profile Unbuffered DIMM)

- Measures only 0.72~0.738-inch in height
- Prevents mechanical issues, and improves heat dissipation
- Applicable for space-constrained systems, such as small-size industrial computers and embedded systems



Model	DDR4 VLP UDIMM	DDR3 VLP UDIMM	DDR2 VLP UDIMM
Module Type	VLP UDIMM	VLP UDIMM	VLP UDIMM
Memory Technology	DDR4	DDR3	DDR2
Frequency	2133/2400/2666/2933/3200	1066/1333/1600	533/667/800
Density	4G/8G/16G/32G	1G/2G/4G/8G	1G/2G/4G
Voltage	1.2v	1.5v/1.35v	1.8v
Pin Count	288-Pin	240-Pin	240-Pin
Width	64-Bit	64-Bit	64-Bit
PCB Height	0.738"	0.738"	0.72"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C
Application	IoT / Server & Networking		

Value-Added



VLP SODIMM (Very Low Profile SODIMM) / VLP ECC SODIMM (Very Low Profile ECC SODIMM)

- Measures only 0.7~0.709-inch in height
- Saves up to 40% board space
- Applicable for space-constrained systems, such as small form-factor industrial computers and embedded systems



Model	DDR4 VLP SODIMM	DDR4 VLP ECC SODIMM
Module Type	VLP SODIMM	VLP ECC SODIMM
Memory Technology	DDR4	DDR4
Frequency	2133/2400/2666/2933/3200	2133/2400/2666/2933/3200
Density	4G/8G	4G/8G
Voltage	1.2V	1.2V
Pin Count	260-Pin	260-Pin
Width	64-Bit	72-Bit
PCB Height	0.709"	0.7"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C
Application	IoT / Transportation	

Value-Added



Very Low Profile

VLP RDIMM (Very Low Profile Registered DIMM)

- Measures only 0.738-inch in height
- Prevents mechanical issues, and improves heat dissipation
- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- Applicable for space-constrained systems and systems that require high stability, such as blade servers, 1U rack servers and various embedded systems.



Model	DDR4 VLP RDIMM	DDR3 VLP RDIMM
Module Type	VLP RDIMM	VLP RDIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600
Density	4G/8G/16G/32G	1G/2G/4G/8G
Voltage	1.2v	1.5v/1.35v
Pin Count	288-Pin	240-Pin
Width	72-Bit	72-Bit
PCB Height	0.738"	0.738"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C
Application	Healthcare / Server & Networking	

Value-Added



VLP ECC UDIMM (Very Low Profile ECC Unbuffered DIMM)

- Measures only 0.72~0.738-inch in height
- Prevents mechanical issues, and improves heat dissipation
- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- Applicable for space-constrained, servers and workstations that require high stability



Model	DDR4 VLP ECC UDIMM	DDR3 VLP ECC UDIMM
Module Type	VLP ECC UDIMM	VLP ECC UDIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600
Density	4G/8G/16G/32G	1G/2G/4G/8G
Voltage	1.2v	1.5v/1.35v
Pin Count	288-Pin	240-Pin
Width	72-Bit	72-Bit
PCB Height	0.738"	0.738"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C
Application	Healthcare / Server & Networking	

Value-Added



Mini DIMM

Mini RDIMM

- Supports a built-in temperature-monitoring thermal sensor
- High capacity, high performance and high stability
- Supports ECC error detection and correction
- Measures only 80~82mm long
- Applicable for space-constrained networking, communication, server and embedded system



Model	DDR4 Mini RDIMM
Module Type	(VLP) Mini RDIMM
Memory Technology	DDR4
Frequency	2133/2400/2666
Density	4GB/8GB/16GB
Voltage	1.2v
Pin Count	288-Pin
Width	72-Bit
PCB Height	0.738"/1.23"
Operation Temperature	TC=0°C to 85°C
Application	Server & Networking

Value-Added



Mini ECC UDIMM

- Supports a built-in temperature-monitoring thermal sensor
- High capacity, high performance and high stability
- Supports ECC error detection and correction
- Measures only 80~82mm long
- Applicable for space-constrained networking, communication, server and embedded systems



Model	DDR4 VLP Mini ECC UDIMM
Module Type	VLP Mini ECC UDIMM
Memory Technology	DDR4
Frequency	2133/2400/2666
Density	4G/8G/16G
Voltage	1.2v
Pin Count	288-Pin
Width	72-Bit
PCB Height	0.738"
Operation Temperature	TC=0°C to 85°C
Application	Server & Networking

Value-Added



Wide Temperature

Wide Temp UDIMM (Wide Temperature UDIMM)

- Able to operate in temperatures ranging from -40°C to 85°C
- Uses industrial-grade SDRAM components
- With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges



Model	DDR4 Wide Temp. UDIMM	DDR3 Wide Temp. UDIMM
Module Type	Wide Temperature UDIMM	Wide Temperature UDIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600
Density	4G/8G/16G/32G	2G/4G/8G
Voltage	1.2v	1.5v/1.35v
Pin Count	288-Pin	240-Pin
Width	64-Bit	64-Bit
PCB Height	1.23"	1.18"
Operation Temperature	TC=-40°C to 85°C	TC=-40°C to 85°C
Application	Defense / IoT / Transportation / Factory Automation	

Value-Added



Wide Temp SODIMM (Wide Temperature SODIMM)

- Able to operate in temperatures ranging from -40°C to 85°C
- Uses industrial-grade SDRAM components
- With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges



Model	DDR4 Wide Temp. SODIMM	DDR3 Wide Temp. SODIMM	DDR2 Wide Temp. SODIMM	DDR Wide Temp. SODIMM
Module Type	Wide Temperature SODIMM	Wide Temperature SODIMM	Wide Temperature SODIMM	Wide Temperature SODIMM
Memory Technology	DDR4	DDR3	DDR2	DDR
Frequency	2133/2400/2666/2933/3200	1066/1333/1600	533/667/800	266/333/400
Density	4G/8G/16G/32G	2G/4G/8G	1G/2G	512M/1G
Voltage	1.2v	1.5v/1.35v	1.8v	2.5v/2.6v
Pin Count	260-Pin	204-Pin	200-Pin	200-Pin
Width	64-Bit	64-Bit	64-Bit	64-Bit
PCB Height	1.18"	1.18"	1.18"	1.25"
Operation Temperature	TC=-40°C to 85°C	TC=-40°C to 85°C	TC=-40°C to 85°C	TA=-40°C to 85°C
Application	Defense / IoT / Transportation / Factory Automation			

Value-Added



Wide Temperature

Wide Temp ECC UDIMM (Wide Temperature ECC UDIMM)

- Able to operate in temperatures ranging from -40°C to 85°C
- Uses industrial-grade SDRAM components
- With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges



Model	DDR4 Wide Temperature ECC UDIMM	DDR3 Wide Temperature ECC UDIMM
Module Type	Wide Temperature ECC UDIMM	Wide Temperature ECC UDIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600
Density	4G/8G/16G/32G	2G/4G/8G
Voltage	1.2v	1.5v/1.35v
Pin Count	288-Pin	240-Pin
Width	72-Bit	72-Bit
PCB Height	1.23"	1.18"
Operation Temperature	TC=-40°C to 85°C	TC=-40°C to 85°C
Application	Defense / IoT / Transportation / Factory Automation	

Value-Added



Wide Temp ECC SODIMM (Wide Temperature ECC SODIMM)

- Able to operate in temperatures ranging from -40°C to 85°C
- Uses industrial-grade SDRAM components
- With 30u gold plating PCB to improve anti-oxidation and ensure stability of signal transmission
- Applicable for industrial, defense, aeronautical and vehicular systems that face extreme environmental challenges



Model	DDR4 Wide Tempe. ECC SODIMM	DDR3 Wide Tempe. ECC SODIMM
Module Type	Wide Temperature ECC SODIMM	Wide Temperature ECC SODIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600
Density	4G/8G/16G/32G	2G/4G/8G
Voltage	1.2v	1.5v/1.35v
Pin Count	260-Pin	204-Pin
Width	72-Bit	72-Bit
PCB Height	1.18"	1.18"
Operation Temperature	TC=-40°C to 85°C	TC=-40°C to 85°C
Application	Defense / IoT / Transportation / Factory Automation	

Value-Added



Specialty

Anti-Sulfuration Memory Modules

- World's first anti-sulfuration memory modules for the sulfur-containing environment
- The innovative design is now patented
- Applicable for equipment exposed in highly contaminated environment and electronic equipment used in areas of high-concentration sulfur gas



Model	DDR4 Anti-Sulfuration UDIMM	DDR3 Anti-Sulfuration UDIMM	DDR4 Anti-Sulfuration SODIMM	DDR3 Anti-Sulfuration SODIMM
Module Type	Anti-Sulfuration UDIMM	Anti-Sulfuration UDIMM	Anti-Sulfuration SODIMM	Anti-Sulfuration SODIMM
Memory Technology	DDR4	DDR3	DDR4	DDR3
Frequency	2133/2400/2666/2933/3200	1066/1333/1600	2133/2400/2666/2933/3200	1066/1333/1600
Density	4G/8G/16G/32G	1G/2G/4G/8G	4G/8G/16G/32G	1G/2G/4G/8G
Voltage	1.2v	1.35v/1.5v	1.2v	1.35v/1.5v
Pin Count	288-Pin	240-Pin	260-Pin	204-Pin
Width	64-Bit	64-Bit	64-Bit	64-Bit
PCB Height	1.23"	1.18"	1.18"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C / -40°C to 85°C	TC=0°C to 85°C / -40°C to 85°C
Application	Defense / Healthcare / IoT / Transportation / Factory Automation			
Value-Added				



Model	DDR4 Anti-Sulfuration RDIMM	DDR3 Anti-Sulfuration RDIMM	DDR4 Anti-Sulfuration ECC UDIMM	DDR3 Anti-Sulfuration ECC UDIMM	DDR4 Anti-Sulfuration ECC SODIMM	DDR3 Anti-Sulfuration ECC SODIMM	
Module Type	Anti-Sulfuration RDIMM	Anti-Sulfuration RDIMM	Anti-Sulfuration ECC UDIMM	Anti-Sulfuration ECC UDIMM	Anti-Sulfuration ECC SODIMM	Anti-Sulfuration ECC SODIMM	
Memory Technology	DDR4	DDR3	DDR4	DDR3	DDR4	DDR3	
Frequency	2133/2400/2666/2933/3200	1066/1333/1600	2133/2400/2666/2933/3200	1066/1333/1600	2133/2400/2666/2933/3200	1066/1333/1600	
Density	4G/8G/16G/32G	1G/2G/4G/8G	4G/8G/16G/32G	1G/2G/4G/8G	4G/8G/16G/32G	1G/2G/4G/8G	
Voltage	1.2v	1.5v/1.35v	1.2v	1.35v/1.5v	1.2v	1.35v/1.5v	
Pin Count	288-Pin	240-Pin	288-Pin	240-Pin	260-Pin	204-Pin	
Width	72-Bit	72-Bit	72-Bit	72-Bit	72-Bit	72-Bit	
PCB Height	1.23"	1.18"	1.23"	1.18"	1.18"	1.18"	
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	TC=0°C to 85°C	
Application	Defense / Healthcare / IoT / Transportation / Factory Automation						
Value-Added							

Specialty

32-Bit SODIMM

- Supports the ARM architecture
- Provides the 32-bit ARM architecture with another design option besides on-board memory
- Double seismic certification: RTCA DO-160G / MIL-STD-810G
- Applicable for networking, vehicular, mobile communication and embedded device markets



Model	DDR4 32-Bit SODIMM	DDR3 32-Bit SODIMM
Module Type	32-Bit SODIMM	32-Bit SODIMM
Memory Technology	DDR4	DDR3
Frequency	2133/2400/2666	800/1066/1333
Density	2G/4G/8G	1G/2G/4G
Voltage	1.2v	1.5v
Pin Count	260-Pin	204-Pin
Width	32-Bit	32-Bit
PCB Height	1.18"	1.18"
Operation Temperature	TC=0°C to 85°C	TC=0°C to 85°C
Application	IoT / Transportation	
Value-Added	 	 

SORDIMM (Small Outline ECC Registered DIMM)

- Achieves signal synchronization and stability with the use of a register
- Supports ECC error detection and correction
- Supports a built-in temperature-monitoring thermal sensor
- Applicable for small-sized microserver and networking equipment, such as switches and routers



Model	DDR4 SORDIMM
Module Type	(VLP) SORDIMM
Memory Technology	DDR4
Frequency	2133/2400/2666
Density	4G/8G/16G
Voltage	1.2v
Pin Count	260-Pin
Width	72-Bit
PCB Height	0.738"/1.18"
Operation Temperature	TC=0°C to 85°C
Application	Server & Networking
Value-Added	   

Specialty

XR-DIMM

- Designed for shock and vibration environments
- Innovative design with highly rugged 300-pin connector and mounting holes
- Dual anti-shock and vibration certification: RTCA DO-160G / MIL-STD-810G
- Improves the stability of signal transmission
- Applicable for transportation, defense and aeronautical equipment that requires shock and vibration resistance



Model	DDR4 XR-DIMM
Module Type	XR-DIMM
Memory Technology	DDR4
Frequency	2133/2400
Density	8G/16G
Voltage	1.2v
Pin Count	300-Pin
Width	72-Bit
PCB Height	1.466"
Operation Temperature	TC=-40°C to 85°C
Application	Defense / Transportation

Value-Added



Rugged SODIMM

- Designed with two mounting holes to secure the memory module to the board to achieve shock and vibration resistance
- Dual anti-shock and vibration certification: RTCA DO-160G / MIL-STD-883K
- Applicable for transportation, automation, wind power generation, energy, defense and aeronautical equipment that requires shock and vibration resistance



Model	DDR4 Rugged SODIMM
Module Type	Rugged SODIMM
Memory Technology	DDR4
Frequency	2133/2400/2666/2933/3200
Density	8G/16G/32G
Voltage	1.2v
Pin Count	260-Pin
Width	64-Bit/72-Bit
PCB Height	1.377"
Operation Temperature	TC=0°C to 85°C / -40°C to 85°C
Application	Defense / Transportation

Value-Added





About Apacer

Apacer is a global leader in digital storage solutions devoted to innovative storage technology and services. After 20 years in the industry, we remain dedicated to our belief in “persistence in doing the right things.” Our core values, as always, continue to revolve around reliability and innovation.

The company focuses on embedded applications for a variety of vertical markets, including military, medical, gaming, and industrial, and has become an integration expert in digital storage, innovative applications, and value-added services. Apacer is known for its advanced technologies and product quality and was ranked by Gartner as the top industrial SSD supplier for five consecutive years, from 2012 to 2016. In addition, Apacer is committed to making a positive impact on societal issues and has joined the **Responsible Business Alliance (RBA)**, which is formerly known as Electronic Industry Citizenship Coalition (EICC), a coalition promoting **corporate social responsibility (CSR)** within the global electronics supply chain. We believe that the success of a corporation is marked not by profit but by how we benefit others, whether by caring for the environment or making contributions to society.



Compliance and Associations





The Most Reliable Memory For Industries

Global Presence

Taiwan (Headquarters)

Apacer Technology Inc.
Tel: +886-2-2267-8000
Fax: +886-2-2267-2261
Industrial@apacer.com

Japan

Apacer Technology Corp.
Tel: +81-3-5419-2668
Fax: +81-3-5419-0018
jpservices@apacer.com

U.S.A.

Apacer Memory America, Inc.
Tel: +1-408-518-8699
Fax: 1-510-249-9551
ssdsales@apacerus.com

Europe

Apacer Technology B.V.
Tel: +31-40-267-0000
Fax: +31-40-290-0686
sales@apacer.nl

India

Apacer Technologies Pvt. Ltd.
Tel: +91-80-41529061~3
Fax: +91-80-41700215
sales_India@apacer.com

Shanghai

Apacer Electronic(Shanghai) Co., Ltd.
Tel: +86-21-6228-9939
Industrial@apacer.com

